SDAS226A - DECEMBER 1982 - REVISED JANUARY 1995

- Local Bus-Latch Capability
- Choice of True or Inverting Logic
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

DEVICE	OUTPUT	LOGIC
SN74ALS620A	3 state	Inverting
SN74ALS621A	Open collector	True
SN74ALS623A, SN74AS623	3 state	True

(TOP VIEW) OEAB [20 🛭 V_{CC} 19 OEBA А1 [2 A2 [18 B1 3 A3 [B2 17 A4 🛮 5 16**∏** B3 A5 [6 15 □ B4 **∏** B5 A6 ∏ 7 14 A7 **∏** 8 13**∏** B6 A8 [9 12 ∏ B7 GND [] 10 11 **∏** B8

DW OR N PACKAGE

description

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and OEBA) inputs.

The output-enable inputs disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this transceiver configuration. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical for the SN74ALS621A, SN74ALS623A, and SN74AS623 or complementary for the SN74ALS620A.

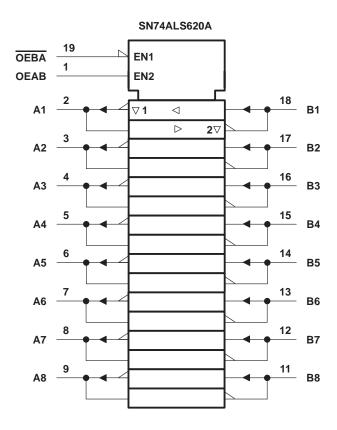
The -1 versions of the SN74ALS620A and SN74ALS621A are identical to the standard versions, except that the recommended maximum I_{OI} is increased to 48 mA in the -1 versions.

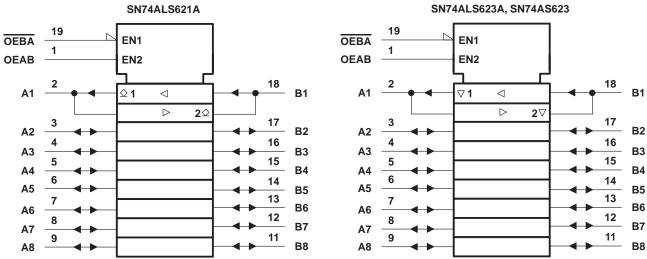
The SN74ALS620A, SN74ALS621A, SN74ALS623A, and SN74AS623 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INPUTS		OPERATION		
OEBA OEAB		SN74ALS620A	SN74ALS621A SN74ALS623A SN74AS623	
L	L	B data to A bus	B data to A bus	
Н	Н	A data to B bus	A data to B bus	
Н	L	Isolation	Isolation	
L	Н	B data to A bus, A data to B bus	B data to A bus, A data to B bus	

logic symbols†

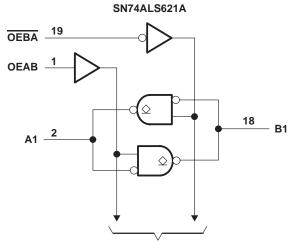




[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagrams (positive logic)

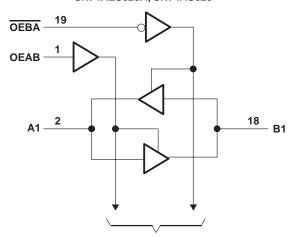
SN74ALS620A OEBA 19 OEAB 1 18 B1



To Seven Other Transceivers

To Seven Other Transceivers

SN74ALS623A, SN74AS623



To Seven Other Transceivers

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, T _A : SN74ALS620A, SN74ALS623A	0°C to 70°C
Storage temperature range6	5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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recommended operating conditions

		SN74ALS620A SN74ALS623A			UNIT
		MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
IOH	High-level output current			-15	mA
loL	Low-level output current			24	mA
T _A	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN74ALS620A SN74ALS623A		-	UNIT
				MIN	TYP [†]	MAX	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	<u>)</u>		
Vон	VOH	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		V
		∨CC = 4.5 ∨	$I_{OH} = -15 \text{ mA}$	2			
\/a:		V22 - 45 V	I _{OL} = 12 mA		0.25	0.4	V
VOL		$V_{CC} = 4.5 \text{ V}$	$I_{OL} = 24 \text{ mA}^{\ddagger}$		0.35	0.5	\ \ \
ı.	Control inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1	mA
t ₁	A or B ports	vCC = 9.9 v	V _I = 5.5 V			0.1	mA
I	Control inputs		\/. 0.7.\/			20	
lН	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20	μΑ
l	Control inputs	V 55V	\/. 0.4\/			-0.1	mA
IIL	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.1	mA
Io¶		V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	mA
			Outputs high		24	34	
	SN74ALS620A	$V_{CC} = 5.5 V$	Outputs low		31	44	
			Outputs disabled		33	47	mA
Icc			Outputs high		32	43	IIIA
	SN74ALS623A	$V_{CC} = 5.5 V$	Outputs low		39	50	
			Outputs disabled		42	55	1

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

 $[\]ddagger$ Applies only to the -1 version and only if VCC is between 4.75 V and 5.25 V

 $[\]S$ For I/O ports, the parameters $I_{\hbox{\scriptsize IH}}$ and $I_{\hbox{\scriptsize IL}}$ include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	112 = 000;		,	UNIT	
			SN74AL	S620A	SN74AL	S623A	
			MIN	MAX	MIN	MAX	
t _{PLH}	А		2	10	2	13	ns
^t PHL	A	В	2	10	3	11	115
t _{PLH}	В	A	2	10	2	13	ns
^t PHL		А	2	10	3	11	115
^t PZH	OEBA	^	3	17	5	22	ns
t _{PZL}	OEBA	А	5	25	5	22	115
^t PHZ	OEBA	٨	2	12	2	16	ns
^t PLZ	OEBA	А	3	18	2	19	115
^t PZH	OFAR	В	3	18	5	22	ns
^t PZL	OEAB	В	5	25	5	22	115
^t PHZ	OEAB	В	2	12	2	16	ns
^t PLZ	OLAB	ט	3	18	2	19	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}		 7 V
Input voltage, V _I : All inputs and I/O ports		 7 V
Operating free-air temperature range, T _A :	SN74ALS621A .	 0°C to 70°C
Storage temperature range		 -65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN74ALS621A		UNIT	
		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
Vон	High-level output voltage			5.5	V
la.	Low lovel output ourrant			24	mA
lOL	Low-level output current			48§	mA
TA	Operating free-air temperature	0		70	°C

 $[\]S$ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CO	NUDITIONS	SN	74ALS62	1A	UNIT
	PARAMETER	TEST CONDITIONS		MIN TYPT		MAX	UNII
٧ıĸ		$V_{CC} = 4.5 V,$	$I_1 = -18 \text{ mA}$			-1.5	V
IOH		$V_{CC} = 4.5 V,$	V _{OH} = 5.5 V			0.1	mA
\/		V45V	I _{OL} = 24 mA		0.35	0.5	V
VOL		VCC = 4.5 V	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 48 \text{ mA}^{\ddagger}$		0.35	0.5	V
ī	Control inputs	V-2 - 5 5 V	V _I = 7 V			0.1	mA
'1	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1	mA
	Control inputs	V 55V	\/. 27\/			20	
ΊΗ	A or B ports§	$V_{CC} = 5.5 V$,	$V_{I} = 2.7 \text{ V}$			20	μΑ
Ίμ	Control inputs	V 55V				-0.1	A
	A or B ports§	$V_{CC} = 5.5 V$,	$V_{I} = 0.4 \text{ V}$			-0.1	mA
1		V	Outputs high		29	40	mA
Icc		V _{CC} = 5.5 V	Outputs low		35	48	IIIA

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$ $C_L = 50 \text{ pF},$ $R_L = 680 \Omega,$ $T_A = \text{MIN to MAX}$ SN74ALS621A		UNIT
			MIN	MAX	
t _{PLH}	А	В	10	33	ns
t _{PHL}		В	5	20	113
^t PLH	В		10	33	ns
^t PHL	В	A	5	20	115
^t PLH	<u> </u>		10	39	
^t PHL	OEBA	A	12	35	ns
t _{PLH}	OEAB	В	10	39	20
^t PHL	OEAB	В	12	35	ns

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V

[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I : All inputs	7 V
I/O ports	5.5 V
Operating free-air temperature range, TA: SN74AS623	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SN74AS623		3	UNIT
		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
IOH	High-level output current			-15	mA
lOL	Low-level output current			64	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST 00ND	NTIONO	SN				
	PARAMETER	TEST COND	IIIONS	MIN	MIN TYP [‡] MAX		UNIT	
۷ıK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I _{OH} = −2 mA	V _{CC} -2				
Vон		V 45V	$I_{OH} = -3 \text{ mA}$	2.4	3.2		V	
		$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -15 \text{ mA}$	2				
VOL		$V_{CC} = 4.5 V,$	$I_{OL} = 64 \text{ mA}$		0.35	0.55	V	
1.	Control inputs	V F5V	V _I = 7 V		0.1		mA	
11	A or B ports	$V_{CC} = 5.5 V$	V _I = 5.5 V			0.1	IIIA	
	Control inputs	V	\/ı = 2.7.\/			20	^	
lН	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			70	μΑ	
l	Control inputs	V	\/. 0.4\/			-0.5	A	
IIL	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.75	mA	
IoI		$V_{CC} = 5.5 V,$	V _O = 2.25 V	-30		-150	mA	
			Outputs high		57	93		
ICC		$V_{CC} = 5.5 V$	Outputs low		16	189	mA	
			Outputs disabled		71	116		

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

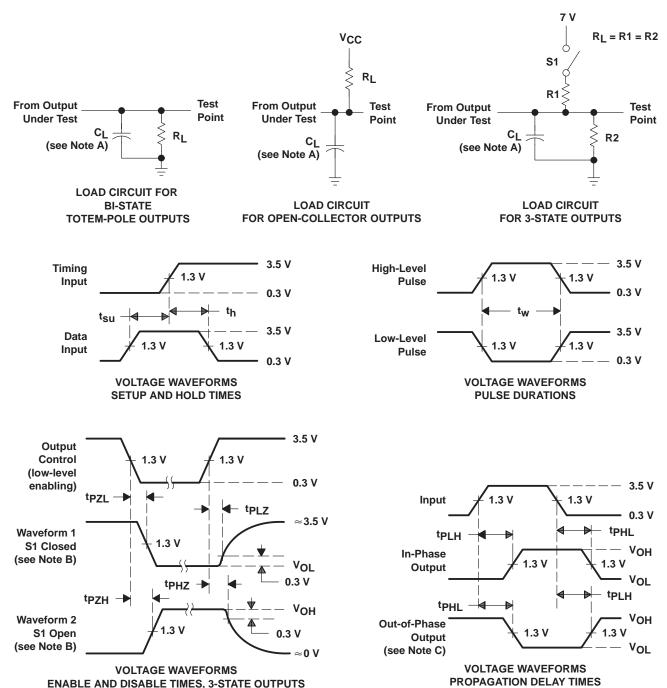
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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5^{\circ}$ $C_{L} = 50 \text{ pF}$ $R1 = 500 \Omega$ $R2 = 500 \Omega$ $T_{A} = \text{MIN to}$ $SN74A$, , , o MAX†	UNIT
			MIN	MAX	
t _{PLH}	A		1	9	no
^t PHL	A	В	1	8	ns
t _{PLH}	В	•	1	9	ns
^t PHL	ם	А	1	8.5	115
^t PZH	OEBA	•	2	11	ns
^t PZL	OEBA	А	2	10	
^t PHZ	 OEBA		1	7.5	
^t PLZ	OEBA	А	1	11.5	ns
^t PZH	OFAR		2	11.5	ns
tPZL	OEAB	В	2	11	115
^t PHZ	OEAB	В	1	7	ne
^t PLZ	OLAD	ט	1	9	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







31-Oct-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN74ALS620ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS620A	Sampl
SN74ALS620ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS620A	Sample
SN74ALS620ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS620A	Sampl
SN74ALS620ADWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS620AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS620AN	Sampl
SN74ALS620ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS620AN	Sampl
SN74ALS621A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621A-1N	Sampl
SN74ALS621A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621A-1N	Samp
SN74ALS621ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS621A	Samp
SN74ALS621ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS621A	Samp
SN74ALS621ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS621A	Samp
SN74ALS621AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621AN	Samp
SN74ALS621ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS621AN	Samp
SN74ALS623A-1DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS623A-1DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS623A-1N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS623ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samp
SN74ALS623ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samp
SN74ALS623ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samp



PACKAGE OPTION ADDENDUM

31-Oct-2013

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS623AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS623AN	Samples
SN74ALS623AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS623ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS623AN	Samples
SN74ALS623ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samples
SN74ALS623ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samples
SN74ALS623ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS623A	Samples
SN74AS623DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS623DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS623N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



PACKAGE OPTION ADDENDUM

31-Oct-2013

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

 \oplus

B0

www.ti.com 14-Jul-2012

TAPE DIMENSIONS

- K0

Cavity

TAPE AND REEL INFORMATION

REEL DIMENSIONS



A0 Dimension designed to accommodate the component width B0 Dimension designed to accommodate the component length K0 Dimension designed to accommodate the component thickness W Overall width of the carrier tape

Pitch between successive cavity centers

◆ A0 **→**

 $\oplus | \oplus$

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS623ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

Ī	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN74ALS623ANSR	SO	NS	20	2000	367.0	367.0	45.0	

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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